Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

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LOC	DIST
AA	00

REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
	B1	ECR-09-009133	22APR2009	TY	SY

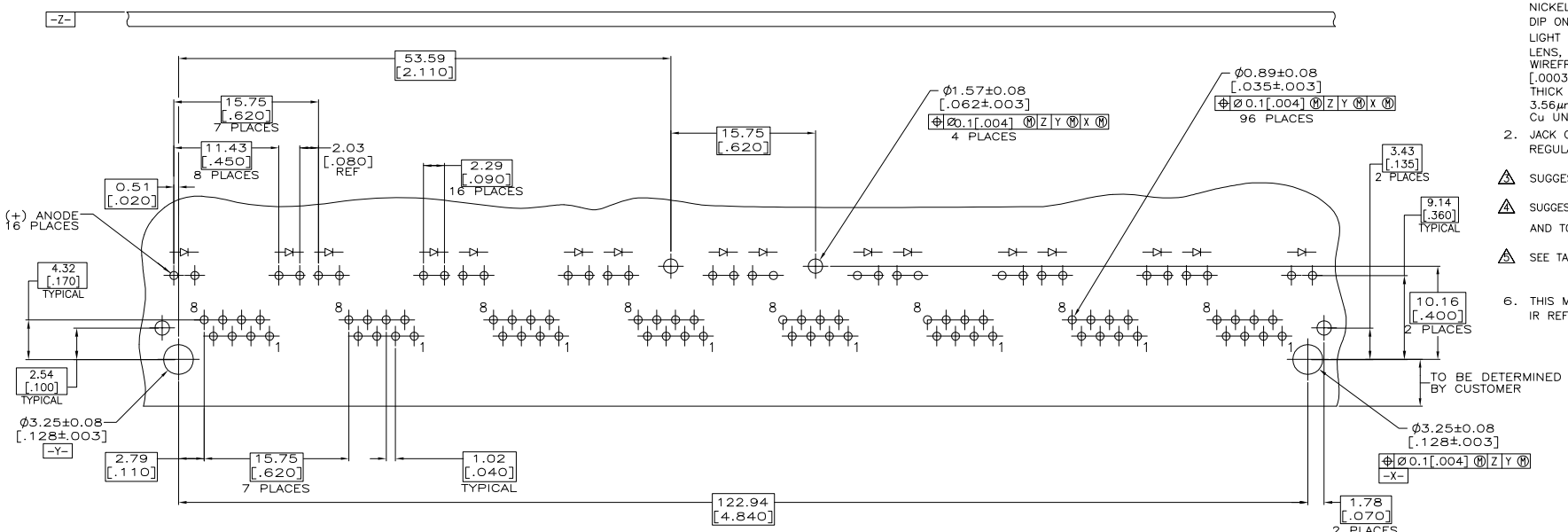
1. MATERIAL:
   HOUSING – HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
   TERMINALS – 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27μm[.000050] MIN THICK HARD GOLD IN LOCALIZED AREA AND 3.81μm [.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] MIN THICK NICKEL UNDERPLATE. CONTACT LUBE ON GOLD PLATED PORTION
   SHIELD – 0.196[.0077] THICK COPPER ALLOY PREPLATED WITH 1.27μm[.000050] MINIMUM SATIN NICKEL WITH 2.03μm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
   LIGHT EMITTING DIODE (LED) – DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89μm [.0003500] THICK Sn/Cu OVER 2.03μm[.000080] THICK Ag OVER 1.02μm[.000040] THICK Cu 3.56μm[.000140] THICK Ni OVER 1.02μm[.000040] Cu UNDERPLATE.
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIIONS PART 68, SUBPART F.

3. SUGGESTED PANEL OPENING DIMENSIONS.

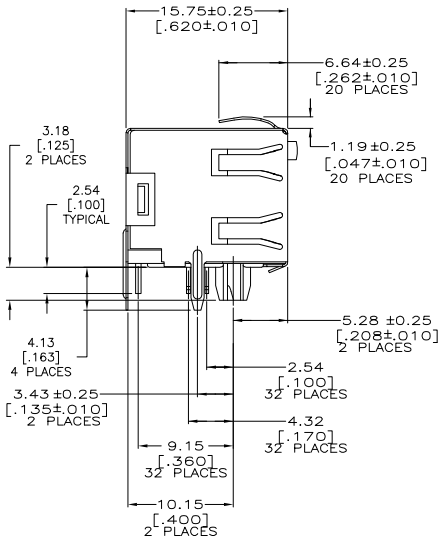
4. SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.

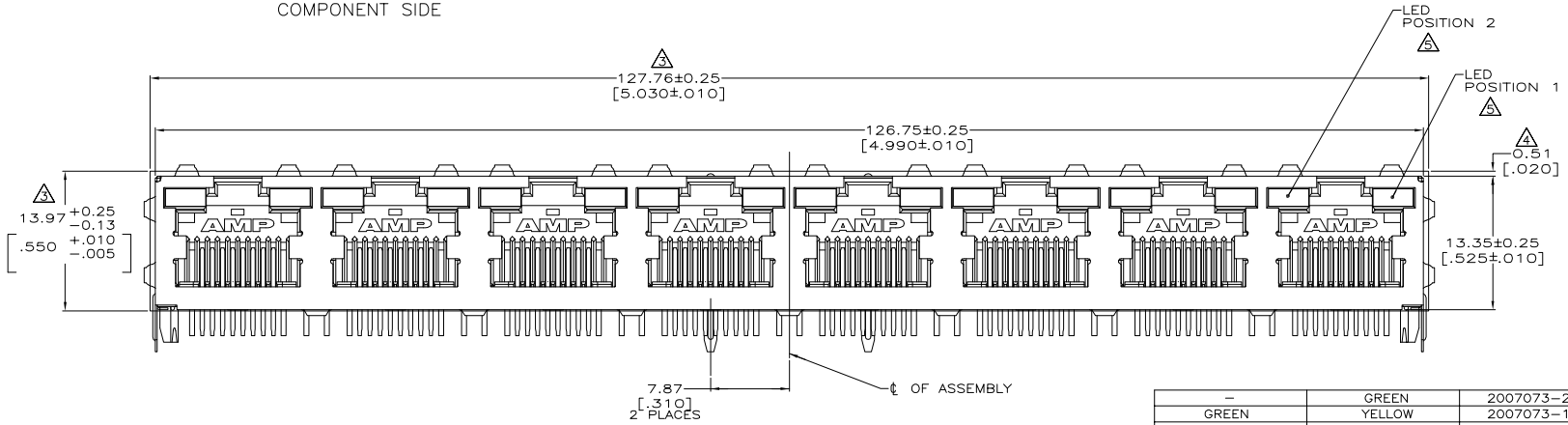
5. SEE TABLE FOR COLOR OF LEDS.

6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
COMPONENT SIDE





–	GREEN	2007073-2
GREEN	YELLOW	2007073-1
POSITION 2	POSITION 1	PART NUMBER
INDICATOR COLOR FOR EACH HOUSING		

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]

TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ± –
1 PLC ± –
2 PLC ± 0.25[.01]
3 PLC ± 0.13[.005]
4 PLC ± –
ANGLES ± –

MATERIAL: SEE NOTE 1
FINISH: SEE NOTE 1

DWN: 16APR2007 B. LATTUCA/L.A.MAYER
CHK: 16APR2007 J. WESTMAN
APVD: 16APR2007 S. FLICKINGER
PRODUCT SPEC: 108-1163-4
APPLICATION SPEC: 114-2154
WEIGHT: –

Tyco Electronics
Tyco Electronics Corporation
Harrisburg, PA 17105-3608

NAME: INVERTED MODULAR JACK ASSEMBLY, 1X8, SHIELDED, BOTTOM TAB, PANEL GROUND, LED

SIZE: A1 | CAGE CODE: 00779 | DRAWING NO: C-2007073 | RESTRICTED TO: –

CUSTOMER DRAWING | SCALE 4:1 | SHEET 1 OF 1 | REV B1